3M introduces an innovative high-performance diamond pad conditioner for oxide CMP

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3M today introduced an innovative high-performance diamond pad conditioner - the 3M Diamond Pad Conditioner A4-55 - for oxide chemical mechanical planarization (CMP) that upholds 3M's commitment to quality, while offering improved cost of ownership.

"3M is committed to the semiconductor industry and is focused on identified customer and industry needs. The new A4-55 pad conditioner is another example of how we're working with our customers to prove that commitment," said Eric Funkenbusch, business unit manager for 3M.

Constructed with a lightweight polycarbonate backing, the new 3M Diamond Pad Conditioner A4-55 offers lower cost of ownership. Like all 3M diamond pad conditioners, it provides high-quality, consistent lot-to-lot performance with superior diamond retention. The 3M A4-55 also optimizes conditioner aggressiveness for extended pad life. In addition, the new 3M pad conditioner offers an extremely flat area of active diamonds for lower nonuniformity and excellent pad planarity as well as consistent debris removal. The exclusive polymer substrate enhances corrosion resistance. Upgraded packaging for the 3M A4-55 also helps provide excellent contamination control and cleanroom compatibility.

The 3M A4-55 is the newest addition to 3M's line of diamond pad conditioners that meet a variety of customer-specific needs for a variety

of manufacturing platforms. The entire line features a mechanical and chemical bond to keep diamonds intact for excellent diamond retention - reducing the possibility of macro-scratching - and improved wafer yields.